

High-Speed N-Channel Power MOSFET

Features:

- Low Drain-to-Source On Resistance ($R_{DS(ON)}$)
- Low Total Gate Charge (Q_G) and Gate-to-Drain Charge (Q_{GD})
- Low Series Gate Resistance (R_G)
- Capable of Short Dead-Time Operation
- RoHS Compliant

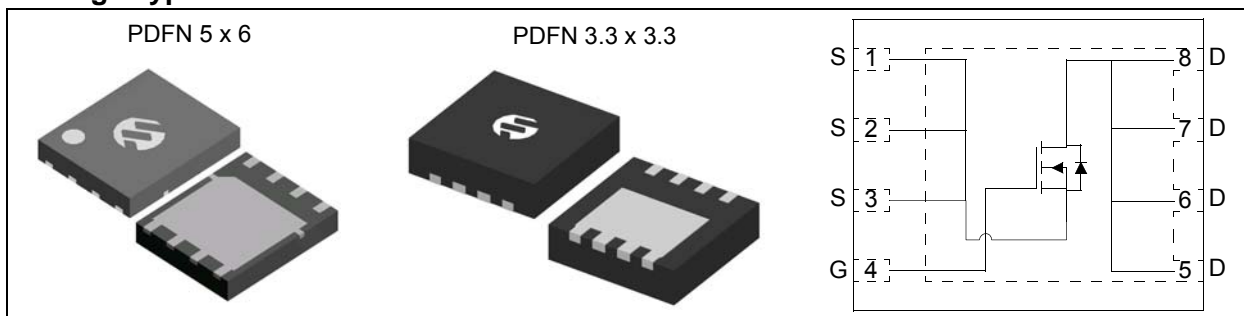
Applications:

- Point-of-Load DC-DC Converters
- High Efficiency Power Management in Servers, Networking, and Automotive Applications

Description:

The MCP87090 is an N-Channel power MOSFET in a popular PDFN 5 mm x 6 mm package, as well as a PDFN 3.3 mm x 3.3 mm package. Advanced packaging and silicon processing technologies allow the MCP87090 to achieve a low Q_G for a given $R_{DS(ON)}$ value, resulting in a low Figure of Merit (FOM). Combined with low R_G , the low FOM of the MCP87090 device allows high efficiency power conversion with reduced switching and conduction losses.

Package Type



Product Summary Table: Unless otherwise indicated, $T_A = +25^\circ\text{C}$

Parameters	Sym	Min	Typ	Max	Units	Conditions
Operating Characteristics						
Drain-to-Source Breakdown Voltage	BV_{DSS}	25	—	—	V	$V_{GS} = 0V, I_D = 250 \mu A$
Gate-to-Source Threshold Voltage	$V_{GS(TH)}$	1.1	1.35	1.7	V	$V_{DS} = V_{GS}, I_D = 250 \mu A$
Drain-to-Source On Resistance	$R_{DS(ON)}$	—	10	12	m Ω	$V_{GS} = 4.5V, I_D = 17A$
		—	8.5	10.5	m Ω	$V_{GS} = 10V, I_D = 17A$
Total Gate Charge	Q_G	—	7.5	10	nC	$V_{DS} = 12.5V, I_D = 17A, V_{GS} = 4.5V$
Gate-to-Drain Charge	Q_{GD}	—	2.8	—	nC	$V_{DS} = 12.5V, I_D = 17A$
Series Gate Resistance	R_G	—	1.8	—	Ω	
Thermal Characteristics						
Thermal Resistance Junction-to-X, 8L 3.3x3.3-PDFN	$R_{\theta JX}$	—	—	66	$^\circ\text{C/W}$	Note 1
Thermal Resistance Junction-to-Case, 8L 3.3x3.3-PDFN	$R_{\theta JC}$	—	—	3.5	$^\circ\text{C/W}$	Note 2
Thermal Resistance Junction-to-X, 8L 5x6-PDFN	$R_{\theta JX}$	—	—	56	$^\circ\text{C/W}$	Note 1
Thermal Resistance Junction-to-Case, 8L 5x6-PDFN	$R_{\theta JC}$	—	—	2.0	$^\circ\text{C/W}$	Note 2

Note 1: $R_{\theta JX}$ is determined with the device surface mounted on a 4-Layer FR4 PCB, with a 1" x 1" mounting pad of 2 oz. copper. This characteristic is dependent on user's board design.

Note 2: $R_{\theta JC}$ is determined using JEDEC 51-14 Method. This characteristic is determined by design.

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1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings †

V_{DS}	+25V
V_{GS}	+10.0V / -8V
I_D , Continuous	
8L 5x6-PDFN	64A, $T_C = +25^\circ\text{C}$
8L 3.3x3.3-PDFN	48A, $T_C = +25^\circ\text{C}$
P_D	
8L 5x6-PDFN	2.2W, $T_A = +25^\circ\text{C}$
8L 3.3x3.3-PDFN	1.8W, $T_A = +25^\circ\text{C}$
T_J, T_{STG}	-55°C to +150°C

E_{AS} Avalanche Energy 84.5 mJ

$I_D = 13A, L = 1\text{ mH}, R_G = 25\Omega$

† **Notice:** Stresses above those listed under “Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational sections of this specification is not intended. Exposure to maximum rating conditions for extended periods may affect device reliability.

DC ELECTRICAL CHARACTERISTICS

Electrical Characteristics: Unless otherwise indicated, $T_A = +25^\circ\text{C}$.						
Parameters	Sym	Min	Typ	Max	Units	Conditions
Static Characteristics						
Drain-to-Source Breakdown Voltage	B_{VDSS}	25	—	—	V	$V_{GS} = 0V, I_D = 250\ \mu\text{A}$
Drain-to-Source Leakage Current	I_{DSS}	—	—	1	μA	$V_{GS} = 0V, V_{DS} = 20V$
Gate-to-Source Leakage Current	I_{GSS}	—	—	100	nA	$V_{DS} = 0V, V_{GS} = 10V/-8V$
Gate-to-Source Threshold Voltage	$V_{GS(TH)}$	1.1	1.35	1.7	V	$V_{DS} = V_{GS}, I_D = 250\ \mu\text{A}$
Drain-to-Source On Resistance	$R_{DS(ON)}$	—	10	12	m Ω	$V_{GS} = 4.5V, I_D = 17A$
		—	8.5	10.5	m Ω	$V_{GS} = 10V, I_D = 17A$
Transconductance	g_{fs}	—	62	—	S	$V_{DS} = 12.5V, I_D = 17A$
Dynamic Characteristics						
Input Capacitance	C_{ISS}	—	580	—	pF	$V_{GS} = 0V, V_{DS} = 12.5V, f = 1\text{ MHz}$
Output Capacitance	C_{OSS}	—	265	—	pF	$V_{GS} = 0V, V_{DS} = 12.5V, f = 1\text{ MHz}$
Reverse Transfer Capacitance	C_{RSS}	—	70	—	pF	$V_{GS} = 0V, V_{DS} = 12.5V, f = 1\text{ MHz}$
Total Gate Charge	Q_G	—	7.5	10	nC	$V_{DS} = 12.5V, I_D = 17A, V_{GS} = 4.5V$
Gate-to-Drain Charge	Q_{GD}	—	2.8	—	nC	$V_{DS} = 12.5V, I_D = 17A$
Gate-to-Source Charge	Q_{GS}	—	1.2	—	nC	$V_{DS} = 12.5V, I_D = 17A$
Gate Charge at $V_{GS(TH)}$	$Q_{G(TH)}$	—	0.8	—	nC	$V_{DS} = 12.5V, I_D = 17A$
Output Charge	Q_{OSS}	—	5	—	nC	$V_{DS} = 12.5V, V_{GS} = 0$
Turn-On Delay Time	$t_{d(on)}$	—	2.5	—	ns	$V_{DS} = 12.5V, V_{GS} = 4.5V, I_D = 17A, R_G = 2\Omega$
Rise Time	t_r	—	9.3	—	ns	$V_{DS} = 12.5V, V_{GS} = 4.5V, I_D = 17A, R_G = 2\Omega$
Turn-Off Delay Time	$t_{d(off)}$	—	5.3	—	ns	$V_{DS} = 12.5V, V_{GS} = 4.5V, I_D = 17A, R_G = 2\Omega$
Fall Time	t_f	—	2.9	—	ns	$V_{DS} = 12.5V, V_{GS} = 4.5V, I_D = 17A, R_G = 2\Omega$
Series Gate Resistance	R_G	—	1.8	—	Ω	
Diode Characteristics						
Diode Forward Voltage	V_{FD}	—	0.8	1	V	$I_S = 17A, V_{GS} = 0V$
Reverse Recovery Charge	Q_{RR}	—	11	—	nC	$I_S = 17A, di/dt = 300\text{ A}/\mu\text{s}$
Reverse Recovery Time	t_{rr}	—	11.5	—	nS	$I_S = 17A, di/dt = 300\text{ A}/\mu\text{s}$

DC ELECTRICAL CHARACTERISTICS (CONTINUED)

Electrical Characteristics: Unless otherwise indicated, $T_A = +25^\circ\text{C}$.						
Parameters	Sym	Min	Typ	Max	Units	Conditions
Avalanche Characteristics						
Avalanche Energy	E_{AS}	18	—	—	mJ	$I_D = 6\text{A}$, $L = 1\text{ mH}$, $R_G = 25\Omega$

TEMPERATURE CHARACTERISTICS

Electrical Characteristics: Unless otherwise indicated, $T_A = +25^\circ\text{C}$						
Parameters	Sym	Min	Typ	Max	Units	Conditions
Temperature Ranges						
Operating Junction Temperature Range	T_J	-55	—	+150	$^\circ\text{C}$	
Storage Temperature Range	T_A	-55	—	+150	$^\circ\text{C}$	
Package Thermal Resistances						
Thermal Resistance Junction-to-X, 8L 5x6-PDFN	$R_{\theta JX}$	—	—	56	$^\circ\text{C/W}$	Note 1
Thermal Resistance Junction-to-Case, 8L 5x6-PDFN	$R_{\theta JC}$	—	—	2.0	$^\circ\text{C/W}$	Note 2
Thermal Resistance Junction-to-X, 8L 3.3x3.3-PDFN	$R_{\theta JX}$	—	—	66	$^\circ\text{C/W}$	Note 1
Thermal Resistance Junction-to-Case, 8L 3.3x3.3-PDFN	$R_{\theta JC}$	—	—	3.5	$^\circ\text{C/W}$	Note 2

Note 1: $R_{\theta JX}$ is determined with the device surface mounted on a 4-Layer FR4 PCB, with a 1" x 1" mounting pad of 2 oz. copper. This characteristic is dependent on user's board design.

2: $R_{\theta JC}$ is determined using JEDEC 51-14 Method. This characteristic is determined by design.

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2.0 TYPICAL PERFORMANCE CURVES

Note: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.

Note: Unless otherwise indicated, $T_A = +25^\circ\text{C}$.

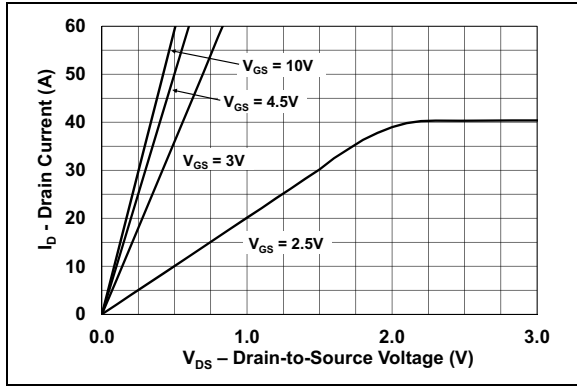


FIGURE 2-1: Typical Output Characteristics.

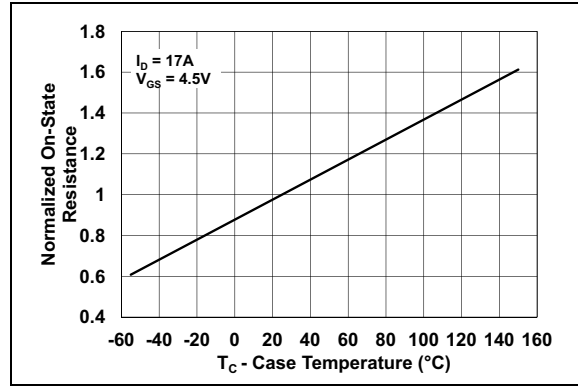


FIGURE 2-4: Normalized On Resistance vs. Temperature.

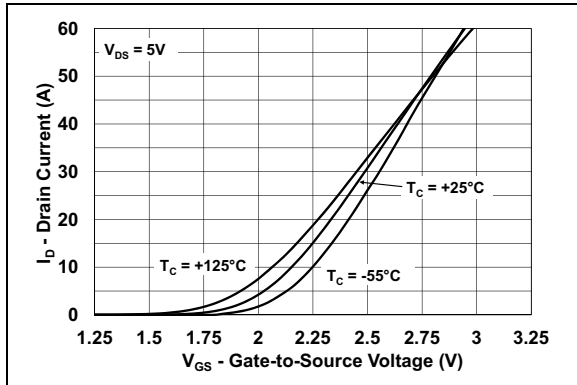


FIGURE 2-2: Typical Transfer Characteristics.

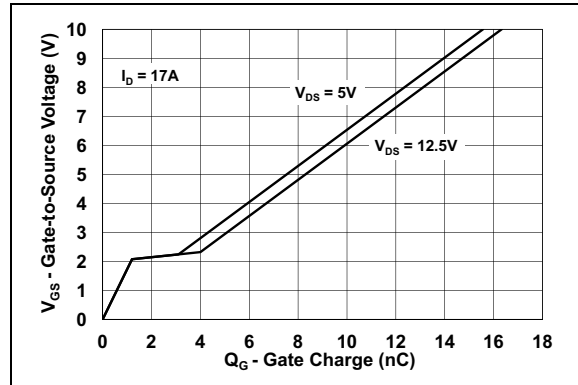


FIGURE 2-5: Gate-to-Source Voltage vs. Gate Charge.

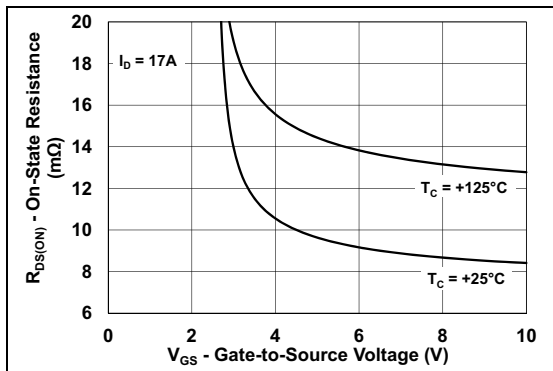


FIGURE 2-3: On Resistance vs. Gate-to-Source Voltage.

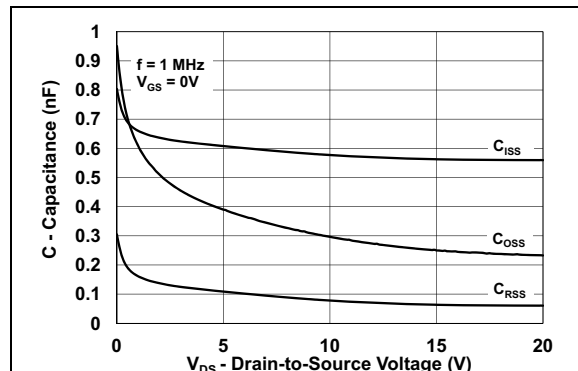


FIGURE 2-6: Capacitance vs. Drain-to-Source Voltage.

Note: Unless otherwise indicated, $T_A = +25^\circ\text{C}$.

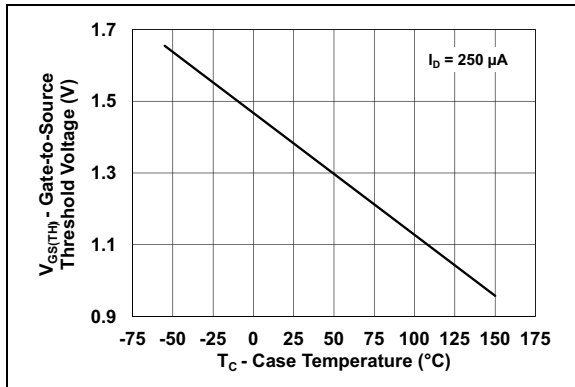


FIGURE 2-7: Gate-to-Source Threshold Voltage vs. Temperature.

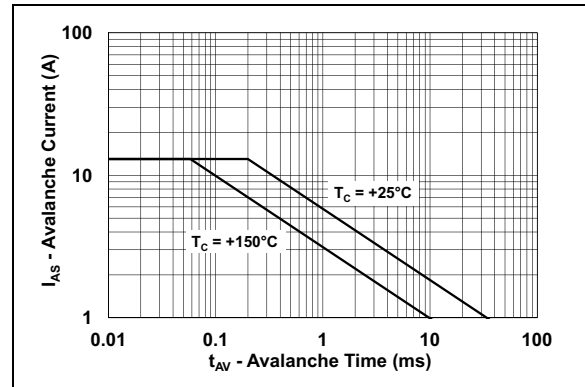


FIGURE 2-10: Single-Pulse Unclamped Inductive Switching.

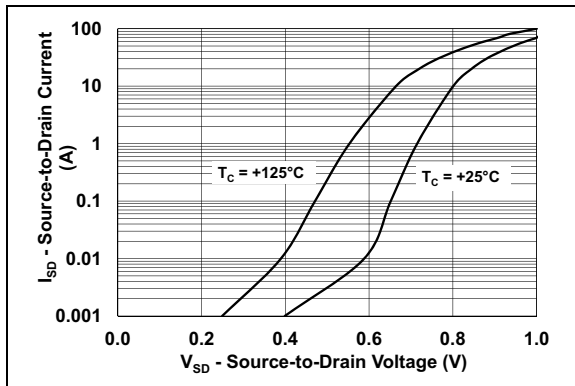


FIGURE 2-8: Source-to-Drain Current vs. Source-to-Drain Voltage.

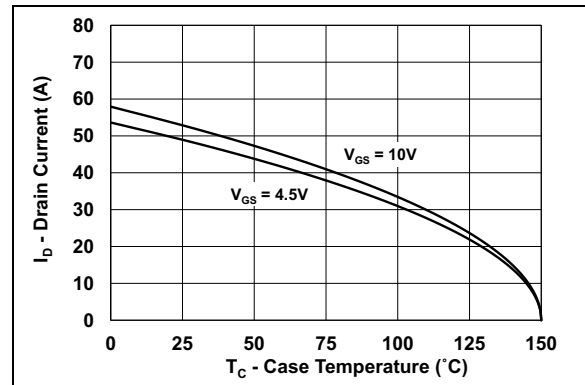


FIGURE 2-11: Maximum Drain Current vs. Temperature 3.3x3.3-PDFN (MCP87090T-U/LC).

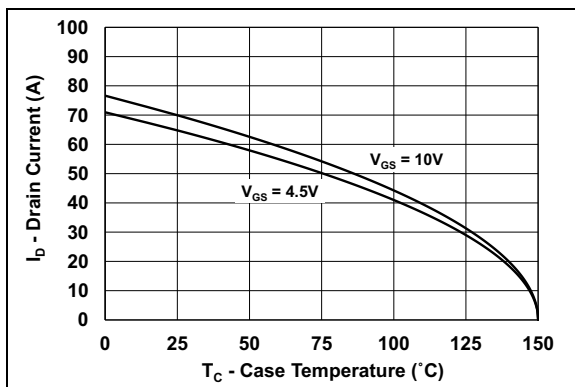


FIGURE 2-9: Maximum Drain Current vs. Temperature 5x6-PDFN (MCP87090T-U/MF).

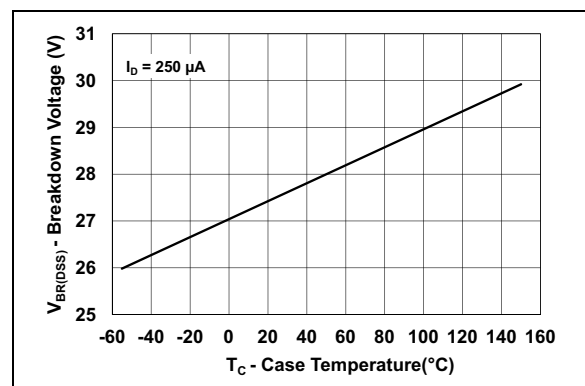


FIGURE 2-12: Drain-to-Source Breakdown Voltage vs. Temperature.

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3.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in [Table 3-1](#).

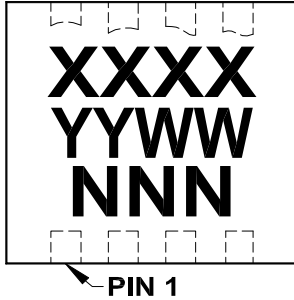
TABLE 3-1: PINOUT DESCRIPTION FOR THE MCP87090

MCP87090	Pin Type	Function
5x6 PDFN, 3.3 x 3.3 PDFN		
1, 2, 3	S	Source pin
4	G	Gate pin
5, 6, 7, 8	D	Drain pin, including exposed thermal pad

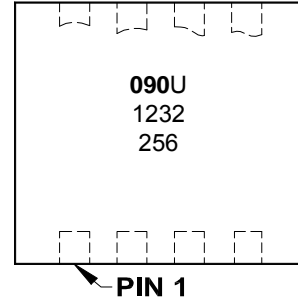
4.0 PACKAGING INFORMATION

4.1 Package Marking Information*

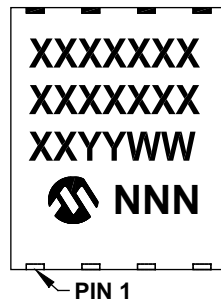
8-Lead PDFN (3.3x3.3x1.0 mm)



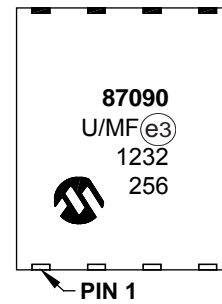
Example



8-Lead PDFN (5x6x1.0 mm)



Example



*RoHS compliant using EU-RoHS exemption: 7(a) - Lead in high-melting-temperature-type solders (i.e. lead-based alloys containing 85% by weight or more lead) can be found on the outer packaging for this package.

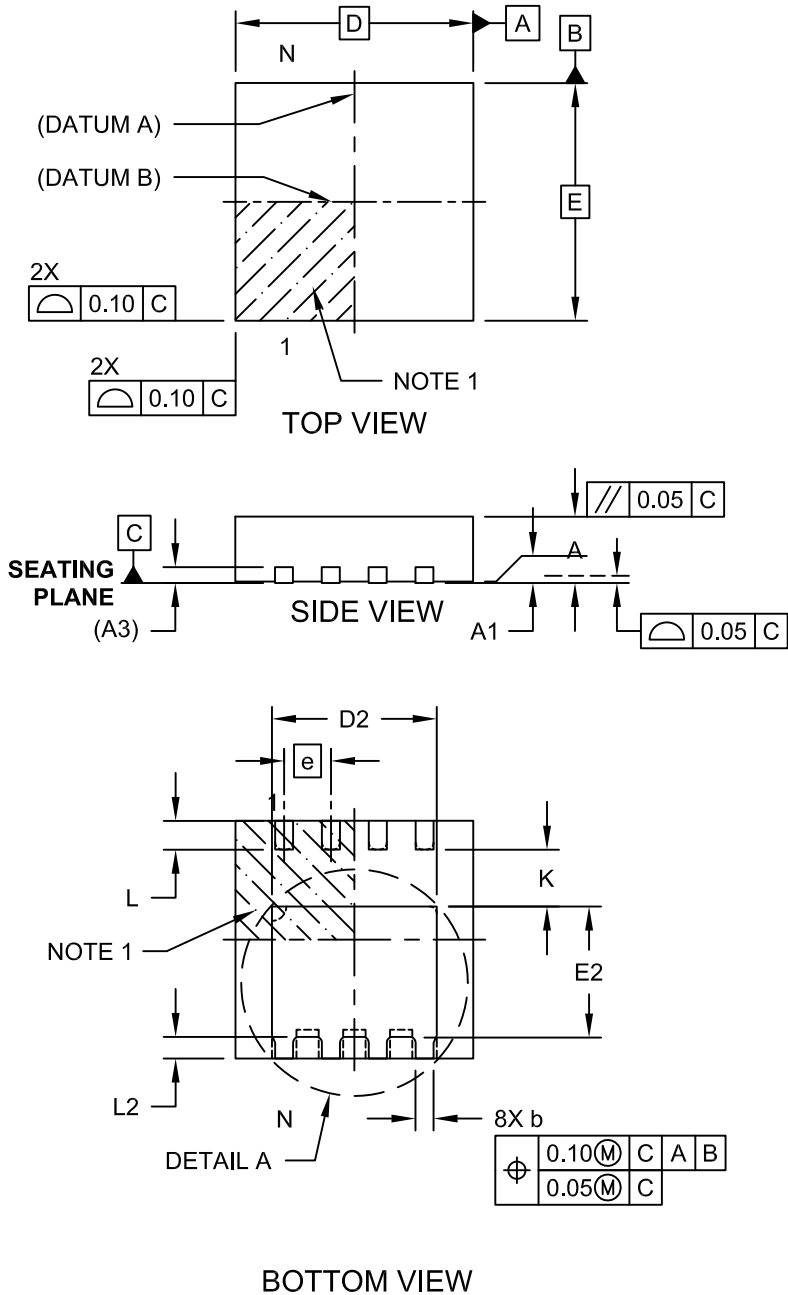
Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week '01')
	NNN	Alphanumeric traceability code
	(e3)	Pb-free JEDEC designator for Matte Tin (Sn)
	*	This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

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8-Lead Power Dual Flatpack No Lead Package (LC) – 3.3x3.3x1.0 mm Body [PDFN]

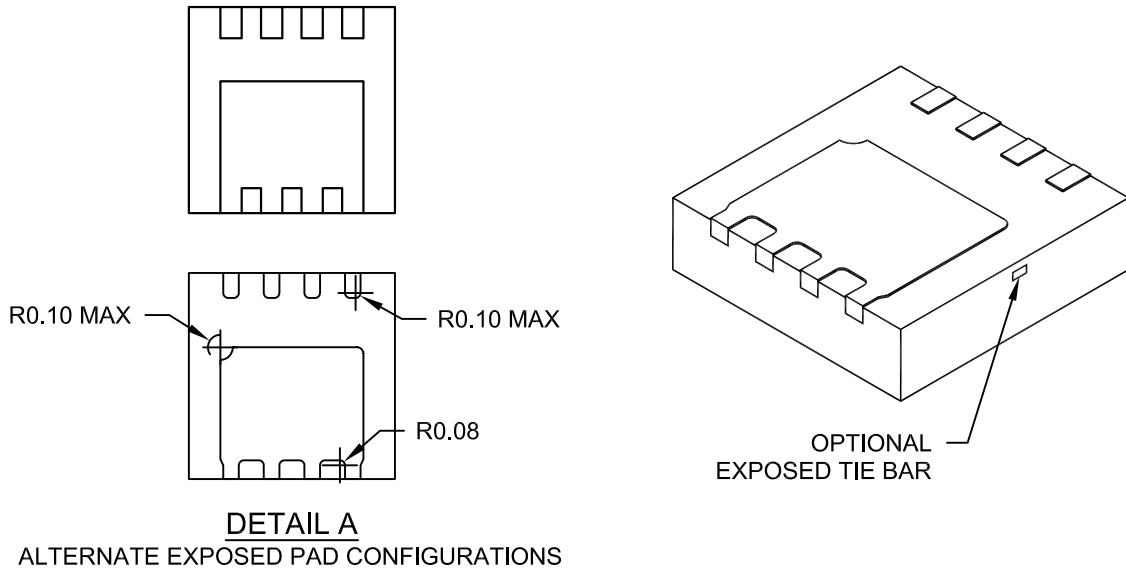
Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Microchip Technology Drawing C04-195A Sheet 1 of 2

8-Lead Power Dual Flatpack No Lead Package (LC) – 3.3x3.3x1.0 mm Body [PDFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Dimension	Units Limits	MILLIMETERS		
		MIN	NOM	MAX
Number of Pins	N	8		
Pitch	e	0.65 BSC		
Overall Height	A	0.80	1.00	1.03
Standoff	A1	0.00	-	0.05
Terminal Thickness	(A3)	0.20 REF		
Overall Length	D	3.30 BSC		
Overall Width	E	3.30 BSC		
Exposed Pad length	D2	2.14	2.29	2.39
Exposed Pad Width	E2	1.66	1.81	1.91
Terminal Width	b	0.25	0.30	0.35
Terminal Length	L	0.30	0.40	0.50
Terminal Length	L2	0.30	-	0.40
Terminal to Exposed Pad	K	0.60	-	-

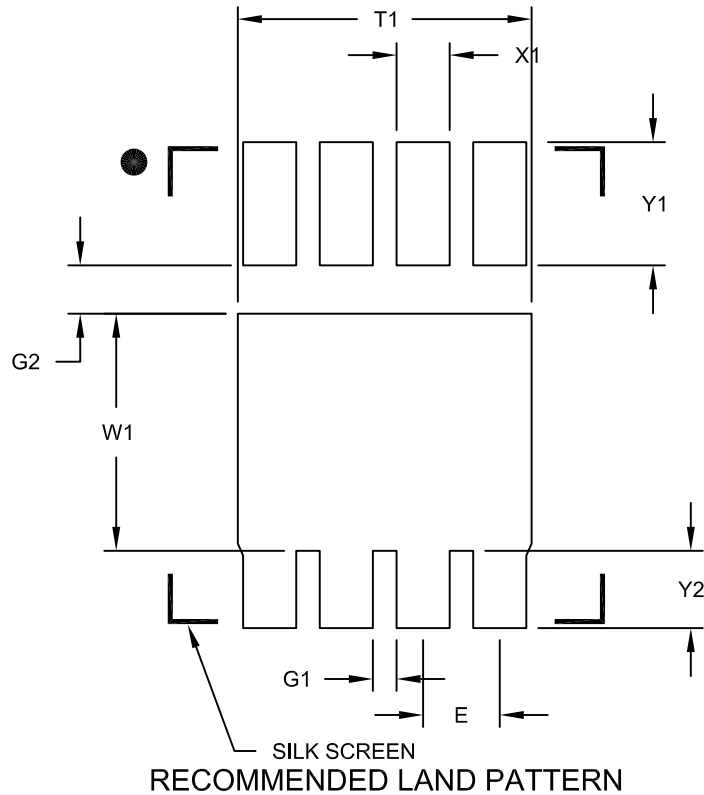
Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package may have one or more exposed tie bars.
3. Package is saw singulated.
4. Package dimension does not include mold flash, protrusions, burrs or metal smearing.
5. Dimensioning and tolerancing per ASME Y14.5M.
 - BSC: Basic Dimension. Theoretically exact value shown without tolerances.
 - REF: Reference Dimension, usually without tolerance, for information purposes only.

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8-Lead Power Dual Flatpack No Lead Package (LC) – 3.3x3.3x1.0 mm Body [PDFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Contact Pitch	E	0.65 BSC		
Center Pad Width	W1			2.01
Center Pad Length	T1			2.49
Distance Between Terminals	G1	0.20		
Terminal Edge to Center Pad	G2	0.41		
Terminal Pad Width (X8)	X1			0.45
Terminal Pad Length (X4)	Y1			1.05
Terminal Pad Length (X8)	Y2			0.66

Notes:

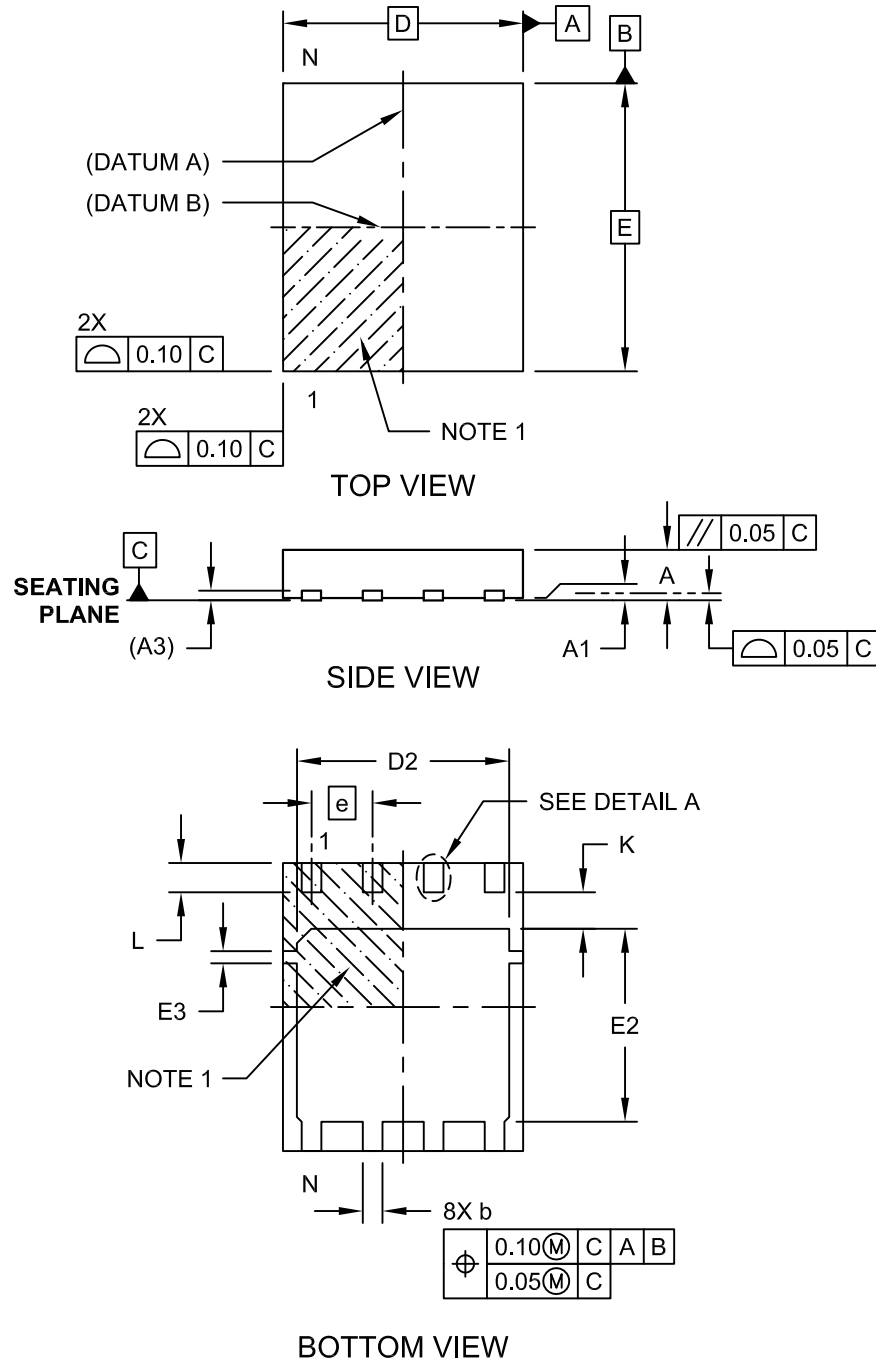
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2195A

8-Lead Power Dual Flatpack No Lead Package (MF) – 5x6x1.0 mm Body [PDFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>

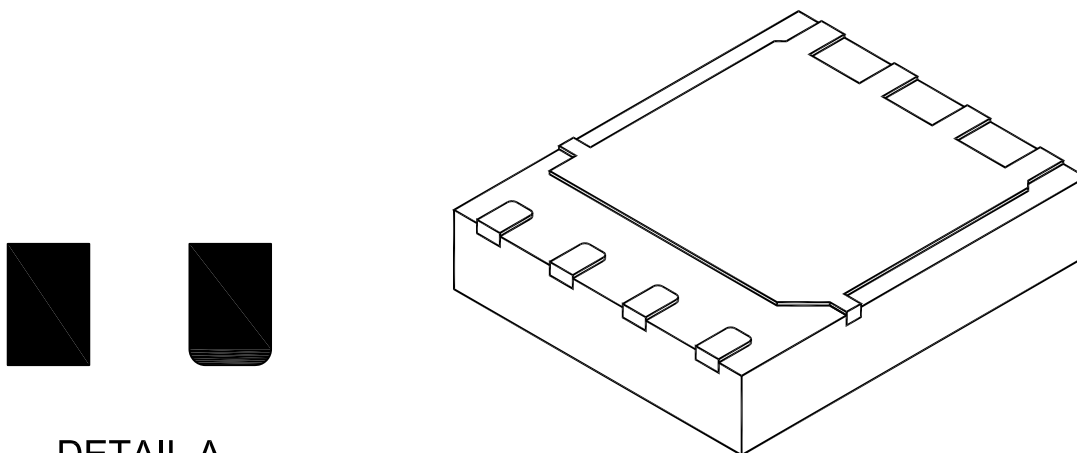


Microchip Technology Drawing C04-188B Sheet 1 of 2

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8-Lead Power Dual Flatpack No Lead Package (MF) – 5x6x1.0 mm Body [PDFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



DETAIL A

ALTERNATE
CONTACT
SHAPES

Dimension	Units	MILLIMETERS		
		Limits	MIN	NOM
Number of Pins	N	8		
Pitch	e	1.27 BSC		
Overall Height	A	0.80	1.00	1.03
Standoff	A1	0.00	-	0.05
Terminal Thickness	(A3)	0.20 REF		
Overall Length	D	5.00 BSC		
Overall Width	E	6.00 BSC		
Exposed Pad length	D2	4.27	4.42	4.52
Exposed Pad Width	E2	3.87	4.02	4.12
Tab Width	E3	0.20	0.25	0.30
Terminal Width	b	0.36	0.41	0.46
Terminal Length	L	0.51	0.61	0.71
Terminal to Exposed Pad	K	0.71	0.76	0.81

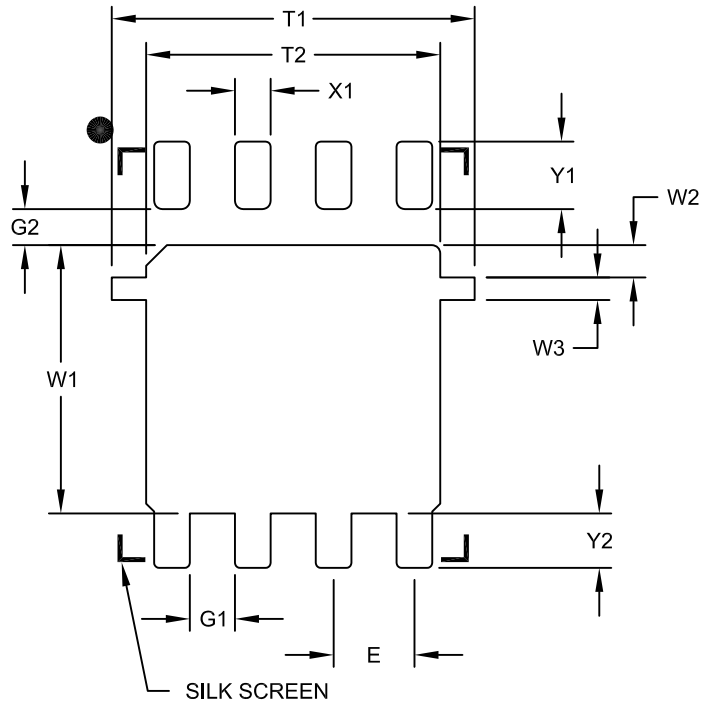
Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated.
3. Package dimension does not include mold flash, protrusions, burrs or metal smearing.
4. Dimensioning and tolerancing per ASME Y14.5M.
BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-188B Sheet 2 of 2

8-Lead Power Dual Flatpack No Lead Package (MF) – 5x6x1.0 mm Body [PDFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

Dimension Limits	Units	MILLIMETERS		
		MIN	NOM	MAX
Contact Pitch	E	1.27 BSC		
Center Pad Width	W1			4.22
Pad Edge to Tab	W2		0.51	
Tab Width	W3		0.35	
Center Pad Length With Tabs	T1			5.70
Center Pad Length	T2			4.62
Distance Between Terminals	G1	0.71		
Terminal To Center Pad (X4)	G2	0.57		
Terminal Pad Width (X8)	X1			0.56
Terminal Pad Length (X4)	Y1			1.06
Terminal Pad Length (X8)	Y2			0.86

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2188A

MCP87090

NOTES:

APPENDIX A: REVISION HISTORY

Revision A (January 2013)

- Original Release of this Document.

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

<u>PART NO.</u>	<u>X</u>	<u>/XX</u>
Device	Temperature Range	Package
Device:	MCP87090T:	N-Channel power MOSFET (Tape and Reel)
Temperature Range:	U	= -55°C to +150°C (Ultra High)
Package:	LC	= High Power Dual Flatpack, No Lead Package (3.3x3.3x1.0 mm Body) (PDFN), 8-lead
	MF	= High Power Dual Flatpack, No Lead Package (5x6x1.0 mm Body) (PDFN), 8-lead

Example:

a) MCP87090T-U/LC: Tape and Reel, Ultra-High Temperature, 8LD 3.3x3.3 PDFN package

b) MCP87090T-U/MF: Tape and Reel, Ultra-High Temperature, 8LD 5x6 PDFN package

Note the following details of the code protection feature on Microchip devices:

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
- Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as “unbreakable.”

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